

Session Program

9-11 Mar 2011

ACES 2011 - Common ATLAS CMS Electronics Workshop for SLHC

Technologies 2

CERN, 222/R-001
Build 222-R-001

Thursday 10 March

10:50

Technologies 2

Session | **Location:** CERN, 222/R-001, Build 222-R-001 | **Conveners:** Philippe Farthouat, Geoff Hall

10:50-11:20 **Advanced packaging in LETI**

Speaker

David Henry

11:25-11:55

Laminate Based System in Package (SiP) Utilizing High Density Interconnect (HDI) Substrates in High Reliability Applications

Speaker

Ron Nowak

12:00-12:15 **Experience with the use of C4**

Speaker

Ken Wyllie

12:20-12:50 **Bump bonding large and thin chips**

Speaker

Thomas Fritzsche

13:00